L Number	Hits	Search Text	DB	Time stamp
1	2	"20040056338"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:03
2	3	"6639308"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 09:40
3	1		USPAT	2004/10/06 09:45
4	2809	@ad<=19991216 and (257/666).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:13
5	238	@ad<=19991216 and (257/672).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:05
6	1553	@ad<=19991216 and (257/676).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:08
7	673	@ad<=19991216 and (257/e23.039).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:10
8	1127	@ad<=19991216 and (257/692).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:06
9	200	@ad<=19991216 and (438/111).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:06
10	570	@ad<=19991216 and (438/123).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:06
11	348	@ad<=19991216 and (257/670).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:26
12	571	@ad<=19991216 and (257/677).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:09
13	99	@ad<=19991216 and (257/e23.141).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:10
14	915	@ad<=19991216 and (257/e23.043).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:11

15	52	@ad<=19991216 and (257/e23.045).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:11
16	24	@ad<=19991216 and (257/e23.05).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:11
17	330	@ad<=19991216 and (257/e23.052).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:12
18	303	@ad<=19991216 and (257/e23.066).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:12
19	83	@ad<=19991216 and (257/666).ccls. and 'lead frame' and 'notch'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:13
20	559	@ad<=19991216 and (361/813).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:21
21	76	@ad<=19991216 and 'lead frame' and 'tie bar' and 'notch'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 10:58
22	2	@ad<=19991216 and 'chip' same 'lead frame' and 'various' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:01
23	2	("6239487").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:00
24	2	@ad<=19991216 and 'lead frame' and 'various' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:37
25	164	@ad<=19991216 and 'lead frame' and 'different' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
26	57	@ad<=19991216 and 'lead frame' same 'different' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
27	37	@ad<=19991216 and 'semiconductor package' and 'lead frame' and 'different' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:06
29	23	@ad<=19991216 and 'lead frame' same 'variable' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38

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30	108	@ad<=19991216 and 'lead frame' with 'flange'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
31	120	@ad<=19991216 and 'semiconductor package' and 'leadframe' with 'step'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:29
32	1	@ad<=19991216 and 'leadframe' and 'various' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:37
33	31	@ad<=19991216 and 'leadframe' and 'different' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
34	11	@ad<=19991216 and 'leadframe' same 'different' with 'chip' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
35	5	@ad<=19991216 and 'leadframe' same 'variable' with 'size'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
36	11	@ad<=19991216 and 'leadframe' with 'flange'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 11:38
39	1		USPAT	2004/10/06 12:34
40	1		USPAT	2004/10/06 12:34
41	1		USPAT	2004/10/06 12:34
42	1		USPAT	2004/10/06 12:36
43	1		USPAT	2004/10/06 12:37
44	1		USPAT	2004/10/06 12:37
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47	1		USPAT	2004/10/06 12:39
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54	1		USPAT	2004/10/06 12:59
55	1		USPAT	2004/10/06 13:00
56	1		USPAT	2004/10/06 13:01
57	1		USPAT	2004/10/06 13:02

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